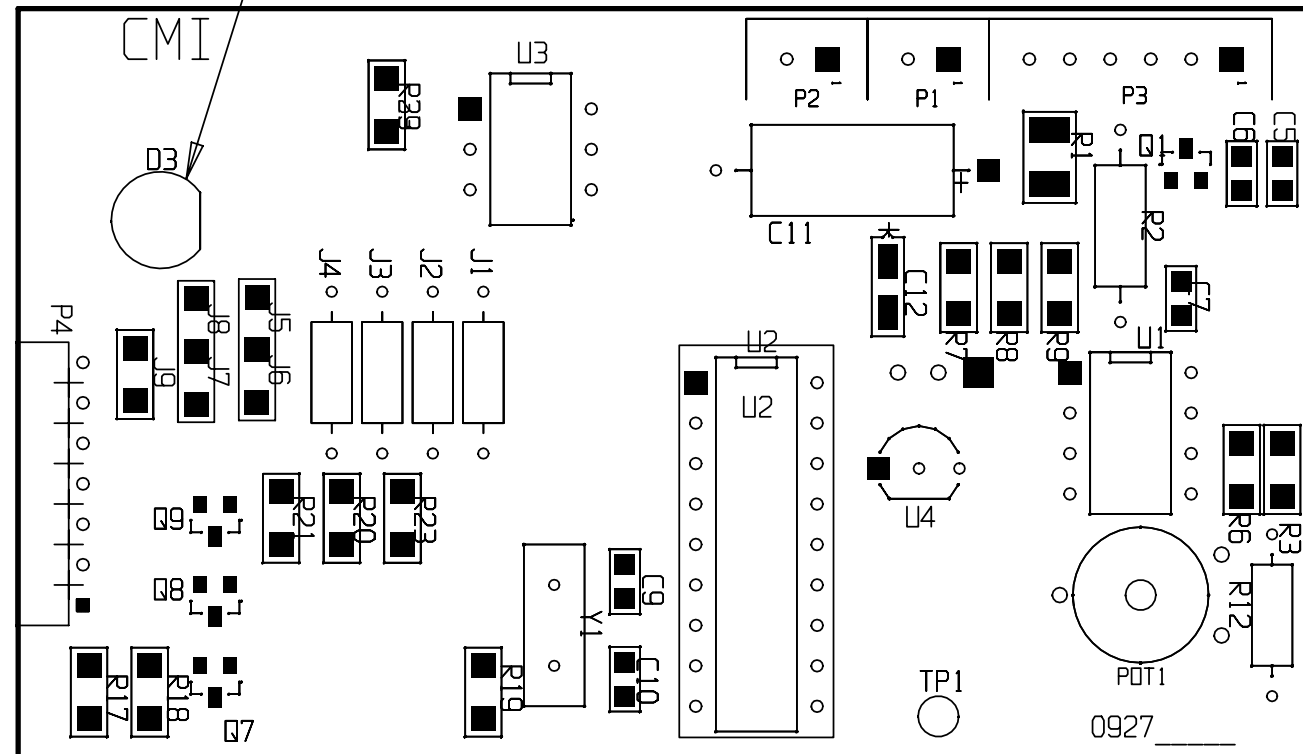


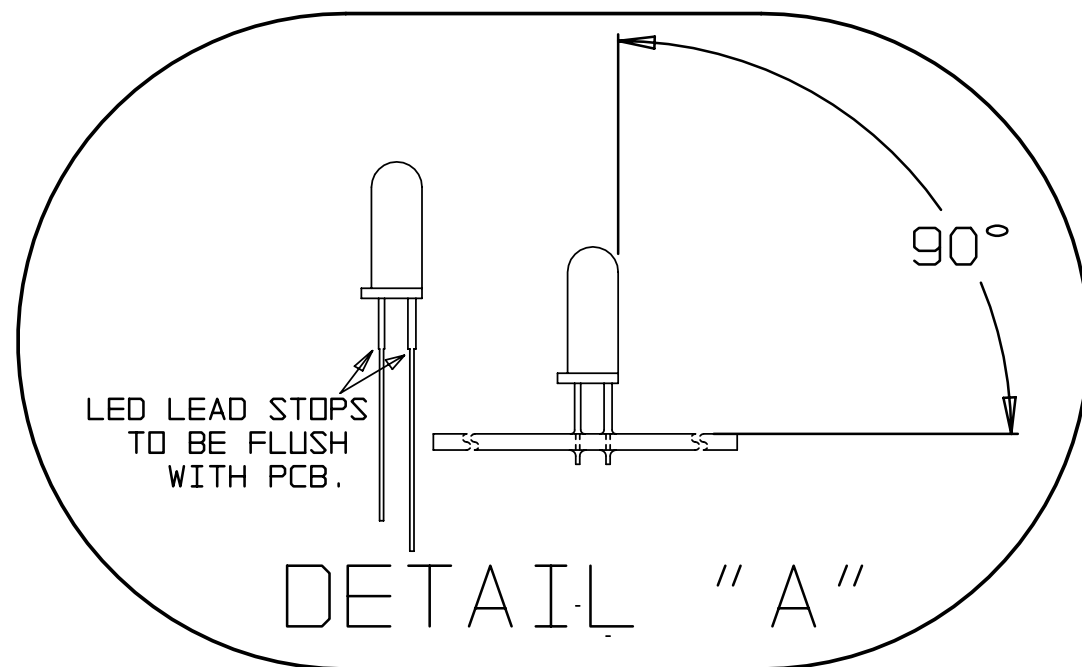
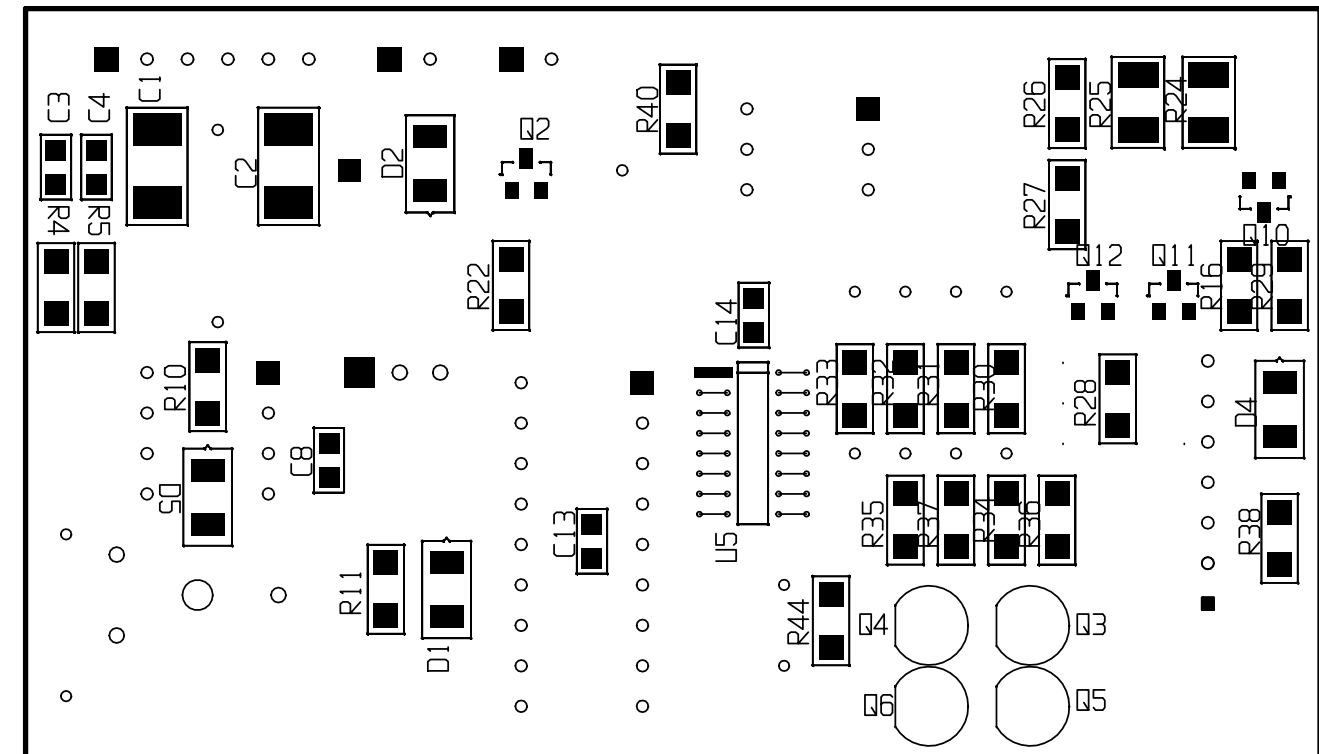
NO.	ECN NO.	REVISIONS	DATE/BY
02 03	006456	SEE SHEET 1	06/26/01 SJS

SEE DETAIL "A"

TOP

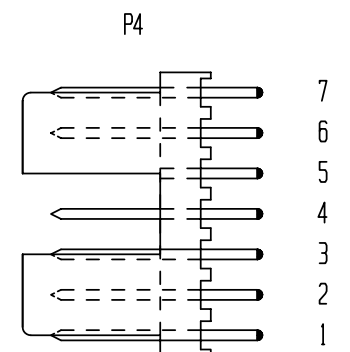


BOTTOM




NOTES:

1. REFER TO SCHEMATIC DIAGRAM AND PARTS LIST FOR REFERENCE DESIGNATIONS AND COMPONENT VALUES
2. MAXIMUM HEIGHT FOR ANY COMPONENT TO BE .450" EXCEPT FOR LED.
3. MAXIMUM COMPONENT LEAD PROJECTION TO BE .085".
4. SOLDERING SHALL BE IN ACCORDANCE WITH IPC-S-815.
5. ASSEMBLIES TO BE CLEANED OF FLUX AND OTHER CONTAMINANTS AFTER SOLDERING.
6. LEADS TO BE VERTICAL TO PCB DURING SOLDERING PROCESS (SEE DETAIL A).
7. CONNECTORS TO BE FLUSH TO PCB DURING SOLDERING PROCESS.
8. Q3-Q6 MUST BE FLUSH AND PERPENDICULAR TO THE BOARD.
9. CUT OFF TERMINAL PIN #5 ON P4 FLUSH TO HEADER.



SEE NOTE #9

 <p>COIN MECHANISMS INC. 400 REGENCY DR. GLENDALE HTGS, IL</p>	TITLE			
	PCB, CTRL, MC62, 12VDC, S13MS, C13MS, T13MS, INH LD, PRI, 7PIN, U2 SOCKET			
	DRAWN	BPP	DATE	8/5/98
	CHKD		DATE	
<p>This drawing is the property of and contains proprietary information of Coin Mechanisms, Inc. The drawing shall be returned upon request and is not to be copied or disclosed without written authorization and will not be used in any way detrimental to the interest of Coin Mechanisms, Inc.</p>	APP		DATE	
	DWG NO. 09270293			REV 3
	SIZE B	SCALE X=X	SHT 2 OF 3	